

Stellaris® LM3S600 RevC2 Errata

This document contains known errata at the time of publication for the Stellaris LM3S600 microcontroller. The table below summarizes the errata and lists the affected revisions. See the data sheet for more details.

See also the ARM® Cortex™-M3 errata, ARM publication number PR141-PRDC-007452 v9.0.

Table 1. Revision History

Date	Revision	Description
August 2011	2.5	■ Added issue "Standard R-C network cannot be used on RST to extend POR timing" on page 4.
		■ Clarified issue "General-purpose timer 16-bit Edge Count or Edge Time mode does not load reload value" on page 6 to include Edge-Time mode.
July 2010	2.4	■ Added issue "The RTRIS bit in the UARTRIS register is only set when the interrupt is enabled" on page 7.
April 2010	2.3	■ Removed issue "Setting Bit 7 in I2C Master Timer Period (I2CMTPR) register may have unexpected results". The data sheet description has changed such that this is no longer necessary.
		■ Minor edits and clarifications.
February 2010	2.2	■ Added issue "The General-Purpose Timer match register does not function correctly in 32-bit mode" on page 6.
		■ Added issue "Setting Bit 7 in I2C Master Timer Period (I2CMTPR) register may have unexpected results".
Jan 2010	2.1	■ "Hard Fault possible when waking from Sleep or Deep-Sleep modes and Cortex-M3 Debug Access Port (DAP) is enabled" has been removed and the content added to the LM3S600 data sheet.
Dec 2009	2.0	Started tracking revision history.

Table 2. List of Errata

Erratum Number	Erratum Title	Module Affected	Revision(s) Affected
1.1	JTAG INTEST instruction does not work	JTAG and Serial Wire Debug	C2
2.1	MOSC verification circuit does not detect all failures of the main oscillator	System Control	C2
2.2	Excessive input pin current when level exceeds V _{DD}	System Control	C2
2.3	LDO Current Limit interrupt does not function properly	System Control	C2
2.4	LDO Power Unregulated interrupt unpredictable after LDO voltage adjustments	System Control	C2
2.5	PLL Lock Raw Interrupt Status triggers when PLL is powered down	System Control	C2
2.6	I/O buffer 5-V tolerance issue	System Control	C2

Erratum Number	Erratum Title	Module Affected	Revision(s) Affected
2.7	Standard R-C network cannot be used on RST to extend POR timing	System Control	C2
3.1	GPIO input pin latches in the Low state if pad type is open drain	GPIO	C2
3.2	GPIO pins may glitch during power supply ramp up	GPIO	C2
4.1	General-purpose timer Edge Count mode count error when timer is disabled	General-Purpose Timers	C2
4.2	General-purpose timer 16-bit Edge Count or Edge Time mode does not load reload value	General-Purpose Timers	C2
4.3	The General-Purpose Timer match register does not function correctly in 32-bit mode	General-Purpose Timers	C2
5.1	The RTRIS bit in the UARTRIS register is only set when the interrupt is enabled	UART	C2

1 JTAG and Serial Wire Debug

1.1 JTAG INTEST instruction does not work

Description:

The JTAG INTEST (Boundary Scan) instruction does not properly capture data.

Workaround:

None.

Silicon Revision Affected:

C2

2 System Control

2.1 MOSC verification circuit does not detect all failures of the main oscillator

Description:

The MOSC verification circuit does not detect all MOSC (main oscillator) failures. In the case where the MOSC clock verification timer function has been enabled by the MOSCVER bit in the **Run-Mode Clock Configuration (RCC)** register, and a MOSC failure is detected, the main clock tree is supposed to immediately switch to a working clock and generate an interrupt to the core. The MOSC verification circuit does not always detect the failure, so the device continues to be clocked by the failed MOSC clock source.

Workaround:

An external clock verification circuit must be used to guarantee the detection of a main oscillator failure. For example, a general-purpose timer can be used to generate a periodic signal to an external circuit that monitors the oscillation of that signal. If the external circuit detects that the signal has stopped oscillating, the circuit can assert the hardware reset pin of the controller.

2 Texas Instruments August 04, 2011/Rev. 2.5

Silicon Revision Affected:

C2

2.2 Excessive input pin current when level exceeds V_{DD}

Description:

When the voltage on an input pin is driven above V_{DD} , excessive current is sunk through the input pin. For example, if a pin is configured as a GPIO input and pulled-up to 5 volts with a 1K W resistor, the V_{IH} level is only 4.4 volts, meaning I_{IH} is 0.64 mA. This violates the 5-V tolerance specification.

Workaround:

If the device driving the input pin above V_{DD} cannot source enough current to drive the signal to a logic High value, a resistor can be used in series to limit the amount of current being sunk through the pin.

Silicon Revision Affected:

C2

2.3 LDO Current Limit interrupt does not function properly

Description:

The System Control module can be programmed by software to generate an interrupt when the LDO exceeds its current limit. This feature does not function properly in all over-current conditions.

Workaround:

The Current Limit interrupt should not be used. The over-current condition should be ignored by the interrupt controller by always masking the Current Limit interrupt. The CLIM bit in the **Interrupt Mask Control (IMC)** register should always be cleared (0).

Silicon Revision Affected:

C2

2.4 LDO Power Unregulated interrupt unpredictable after LDO voltage adjustments

Description:

The System Control module can be programmed by software to generate an interrupt when the LDO power is unregulated. The interrupt is unpredictable while the LDO voltage is being adjusted. This could incorrectly cause an interrupt or, if the LDOARST bit in the Allow Unregulated LDO to Reset the Part (LDOARST) register is set, a system reset.

Workaround:

The Power Unregulated interrupt should not be used while the LDO voltage is adjusted. While the LDO voltage is adjusted, the unregulated power condition should be ignored by the interrupt controller by always masking the Power Unregulated interrupt. This condition is masked by clearing the LDOIM bit in the **Interrupt Mask Control (IMC)** register.

Silicon Revision Affected:

C2

2.5 PLL Lock Raw Interrupt Status triggers when PLL is powered down

Description:

The PLL Lock Raw Interrupt Status (PLLLRIS) register incorrectly triggers when the PLL is powered down. After reset, by default, the PWRDN bit in the Run-Mode Clock Configuration (RCC) register is set, powering down the PLL. This interrupt will not be promoted to the interrupt controller unless the PLL Lock Interrupt Mask (PLLLIM) bit is set in the Interrupt Mask Control (IMC) register.

Workaround:

If the PLL is not being used, mask the PLL Lock interrupt by clearing the PLLIM bit in the **IMC** register. Only unmask the PLLRIS bit after the PLL has been powered on (PWRDN = 0).

Silicon Revision Affected:

C2

2.6 I/O buffer 5-V tolerance issue

Description:

GPIO buffers are not 5-V tolerant when used in open-drain mode. Pulling up the open-drain pin above 4 V results in high current draw.

Workaround:

When configuring a pin as open drain, limit any pull-up resistor connections to the 3.3-V power rail.

Silicon Revision Affected:

C2

2.7 Standard R-C network cannot be used on RST to extend POR timing

Description:

The standard R-C network on $\overline{\mathtt{RST}}$ does not work to extend POR timing beyond the 10 ms on-chip POR. Instead of following the standard capacitor charging curve, $\overline{\mathtt{RST}}$ jumps straight to 3 V at power on. The capacitor is fully charged by current out of the $\overline{\mathtt{RST}}$ pin and does not extend or filter the power-on condition. As a result, the reset input is not extended beyond the POR.

Workaround:

Add a diode to block the output current from $\overline{\mathtt{RST}}$. This helps to extend the $\overline{\mathtt{RST}}$ pulse, but also means that the R-C is not as effective as a noise filter.

Silicon Revision Affected:

C2

4 Texas Instruments August 04, 2011/Rev. 2.5

3 GPIO

3.1 GPIO input pin latches in the Low state if pad type is open drain

Description:

GPIO pins function normally if configured as inputs and the open-drain configuration is disabled. If open drain is enabled while the pin is configured as an input using the GPIO Alternate Function Select (GPIOAFSEL), GPIO Open Drain Select (GPIOODR), and GPIO Direction (GPIODIR) registers, then the pin latches Low and excessive current (into pin) results if an attempt is made to drive the pin High. The open-drain device is not controllable.

A GPIO pin is not normally configured as open drain and as an input at the same time. A user may want to do this when driving a signal out of a GPIO open-drain pad while configuring the pad as an input to read data on the same pin being driven by an external device. Bit-banging a bidirectional, open-drain bus (for example, I²C) is an example.

Workaround:

If a user wants to read the state of a GPIO pin on a bidirectional bus that is configured as an open-drain output, the user must first disable the open-drain configuration and then change the direction of the pin to an input. This precaution ensures that the pin is never configured as an input and open drain at the same time.

A second workaround is to use two GPIO pins connected to the same bus signal. The first GPIO pin is configured as an open-drain output, and the second is configured as a standard input. This way the open-drain output can control the state of the signal and the input pin allows the user to read the state of the signal without causing the latch-up condition.

Silicon Revision Affected:

C2

3.2 GPIO pins may glitch during power supply ramp up

Description:

Upon completing a POR (power on reset) sequence, the GPIO pins default to a tri-stated input condition. However, during the initial ramp up of the external V_{DD} supply from 0.0 V to 3.3 V, the GPIO pins are momentarily configured as output drivers during the time the internal LDO circuit is also ramping up. As a result, a signal glitch may occur on GPIO pins before both the external V_{DD} supply and internal LDO voltages reach their normal operating conditions. This situation can occur when the V_{DD} and LDO voltages ramp up at significantly different rates. The LDO voltage ramp-up time is affected by the load capacitance on the LDO pin, therefore, it is important to keep this load at a nominal 1 μ F value as recommended in the data sheet. Adding significant more capacitance loading beyond the specification causes the time delay between the two supply ramp-up times to grow, which possibly increases the severity of the glitching behavior.

Workaround:

Ensuring that the V_{DD} power supply ramp up is a fast as possible helps minimize the potential for GPIO glitches. Follow guidelines for LDO pin capacitive loading documented in the electrical section of the data sheet. System designers must ensure that, during the V_{DD} supply ramp-up time, possible GPIO pin glitches can cause no adverse effects to their systems.

Silicon Revision Affected:

C2

4 General-Purpose Timers

4.1 General-purpose timer Edge Count mode count error when timer is disabled

Description:

When a general-purpose timer is configured for 16-Bit Input Edge Count Mode, the timer (A or B) erroneously decrements by one when the Timer Enable (TnEN) bit in the **GPTM Control** (**GPTMCTL**) register is cleared (the timer is disabled).

Workaround:

When the general-purpose timer is configured for Edge Count mode and software needs to "stop" the timer, the timer should be reloaded with the current count + 1 and restarted.

Silicon Revision Affected:

C2

4.2 General-purpose timer 16-bit Edge Count or Edge Time mode does not load reload value

Description:

In Edge Count or Edge Time mode, the input events on the CCP pin decrement the counter until the count matches what is in the **GPTM Timern Match (GPTMTnMATCHR)** register. At that point, an interrupt is asserted and then the counter should be reloaded with the original value and counting begins again. However, the reload value is not reloaded into the timer.

Workaround:

Rewrite the GPTM Timern Interval Load (GPTMTnILR) register before restarting.

Silicon Revision Affected:

C2

4.3 The General-Purpose Timer match register does not function correctly in 32-bit mode

Description:

The **GPTM Timer A Match (GPTMTAMATCHR)** register triggers a match interrupt when the lower 16 bits match, regardless of the value of the upper 16 bits.

Workaround:

None.

Silicon Revision Affected:

C2

5 **UART**

5.1 The RTRIS bit in the UARTRIS register is only set when the interrupt is enabled

Description:

The RTRIS (UART Receive Time-Out Raw Interrupt Status) bit in the UART Raw Interrupt Status (UARTRIS) register should be set when a receive time-out occurs, regardless of the state of the enable RTIM bit in the UART Interrupt Mask (UARTIM) register. However, currently the RTIM bit must be set in order for the RTRIS bit to be set when a receive time-out occurs.

Workaround:

For applications that require polled operation, the RTIM bit can be set while the UART interrupt is disabled in the NVIC using the IntDisable(n) function in the StellarisWare Peripheral Driver Library, where n is 21, 22, or 49 depending whether UART0, UART1 or UART2 is used. With this configuration, software can poll the RTRIS bit, but the interrupt is not reported to the NVIC.

Silicon Revision Affected:

C2

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